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10/699830



FORM PTO-1596 1-31-92 Patent and Trademark Office		RECORDATION FORM CO	
DOCKET NO.: 87391.0500		102598086	
To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereto:			
1. Name of conveying party(ies): Kai-Ye HUANG and Chuan-Jane CHAO <u>11-04-03</u>		2. Name and address of receiving party(ies): Name: <u>WINBOND ELECTRONICS CORPORATION</u> Internal Address: _____	
Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		Street Address: <u>No. 4, Creation Rd. III</u> <u>Science-Based Industrial Park</u> State/ City: <u>Hsinchu,</u> Country: <u>TAIWAN, R.O.C.</u> ZIP: _____	
3. Nature of conveyance: <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other _____		Execution Date: <u>17 October 2003</u> Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	
4. Application number(s) or patent number(s): If the document is being filed together with a new application, the execution date of the application is: <u>November 4, 2003</u>		<u>10699830</u>	
A. Patent Application No(s).		B. Patent No(s).	
Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No			
5. Name and address of party to whom correspondence concerning document should be mailed: Name: <u>BAKER &amp; HOSTETLER LLP</u> Internal Address: _____ Street Address: <u>Washington Square, Suite 1100,</u> <u>1050 Connecticut Avenue, N.W.</u> City: <u>Washington</u> State: <u>DC</u> ZIP: <u>20036</u>		6. Total number of applications and patents involved: <u>1</u> 7. Total fee (37 CFR 3.41) \$ <u>40.00</u> <input checked="" type="checkbox"/> Enclosed (included with application fee) <input type="checkbox"/> Authorized to be charged to deposit account	
		8. Deposit account number: <u>50-2036</u>	
DO NOT USE THIS SPACE			
9. Statement and signature. <i>To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.</i>			
<u>Gregory B. Kang</u> Registration No. <u>45,273</u> Name and Registration No. of Person Signing		<u>Gregory B. Kang</u> <u>Nov 4, 2003</u> Signature Date	
Total number of pages <u>3</u>			
CMB No. 0851-0011 (exp. 4/94)			

11/06/2003 HTECKLU1 00000020 10699830  
40.00 DP

## ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title) \_\_\_\_\_  
METHOD AND TEST STRUCTURES FOR MEASURING INTERCONNECT  
COUPLING CAPACITANCE IN AN IC CHIP

The PATENT RIGHTS referred to in this agreement are:

(check one)  a patent application for this invention, executed by the ASSIGNOR(S)  
 concurrently with this assignment.

U.S. patent application Serial No. \_\_\_\_\_, filed \_\_\_\_\_

a U.S. patent application based on PCT International Application  
 No. \_\_\_\_\_ filed on (date) \_\_\_\_\_ (U.S. patent application  
 Serial No. \_\_\_\_\_, if known).

U.S. patent No. \_\_\_\_\_, issued \_\_\_\_\_.

The PATENT RIGHTS also include all divisions reissues, continuations and extensions of  
 the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

(check one)  U.S. patent rights only.

Worldwide patent rights. In this case, the assignee shall have the right to  
 claim the benefit of the filing date of any U.S. or foreign patent application  
 for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures  
 appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) WINBOND ELECTRONICS CORPORATION

(Address) NO.4, CREATION RD. III, SCIENCE-BASED INDUSTRIAL PARK,  
HSINCHU, TAIWAN, R.O.C.

The ASSIGNEE is:

(check one)  An individual.

A Partnership.

A Corporation of TAIWAN, R.O.C. (specify state or country)

(other) \_\_\_\_\_

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and  
 valuable consideration, receipt of which is acknowledged, hereby assign(s) the following  
 rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable  
 provisions, based on any earlier patent applications for this invention.

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO  
ASSIGNEE: WINBOND ELECTRONICS CORPORATION  
INVENTION TITLE: METHOD AND TEST STRUCTURES FOR  
MEASURING INTERCONNECT COUPLING  
CAPACITANCE IN AN IC CHIP

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

<u>Kai-Ye HUANG</u> Name of sole or first inventor	<u>Kai-Ye Huang</u> Signature	<u>Oct-17-2003</u> Date
<u>Chuan-Jane CHAO</u> Name of second inventor, if any	<u>Chuan-Jane Chao</u> Signature	<u>Oct. 17, 2003</u> Date
_____ Name of third inventor, if any	_____ Signature	_____ Date
_____ Name of fourth inventor, if any	_____ Signature	_____ Date
_____ Name of fifth inventor, if any	_____ Signature	_____ Date
_____ Name of sixth inventor, if any	_____ Signature	_____ Date
_____ Name of seventh inventor, if any	_____ Signature	_____ Date